

REMARKS

Applicant requests the entry of Preliminary Amendment A prior to the first Office action on the merits of the application. This Amendment amends the claims to avoid incurring fees for multiple dependent claims. Claims 3, 4, and 8-12 have been amended by this Amendment. Attached hereto is a marked-up version of the changes made to the claims by this Amendment. The attached page is captioned "Version With Markings To Show Changes Made."

The Commissioner is hereby authorized to charge any fees that may be required during the entire pendency of this application to Deposit Account No. 19-1345.

Respectfully submitted,



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VERSION WITH MARKINGS TO SHOW CHANGES MADEIN THE CLAIMS:

Claims 3, 4, and 8-12 have been amended as follows:

3 (amended). A method according to claim 1 [or claim 2], wherein the semiconductor device package is a surface mount semiconductor device package.

4 (amended). A method according to [any of the preceding claims,] claim 1, further comprising, after encapsulating the coated device/leadframe assembly, removing the coating from non-encapsulated portions of the leadframe.

8 (amended). A semiconductor device package according to [any of claims 5 to 7] claim 5, wherein the semiconductor device is attached to the first portion of the leadframe by an adhesive.

9 (amended). A semiconductor device package according to [any of claims 5 to 7] claim 5, wherein the semiconductor device is attached to the first portion of the leadframe by solder.

10 (amended). A semiconductor device package according to [any of claims 5 to 9] claim 5, wherein the semiconductor device is a surface mount semiconductor device.

11 (amended). A semiconductor device package according to [any of claims 5 to 10] claim 5, wherein the semiconductor device is a power semiconductor device.

12 (amended) A semiconductor device package according to [any of claims 5 to 11] claim 5, wherein the first portion of the leadframe forms a heat sink for the semiconductor device and a surface of the first portion is not covered by the electrically insulating material.